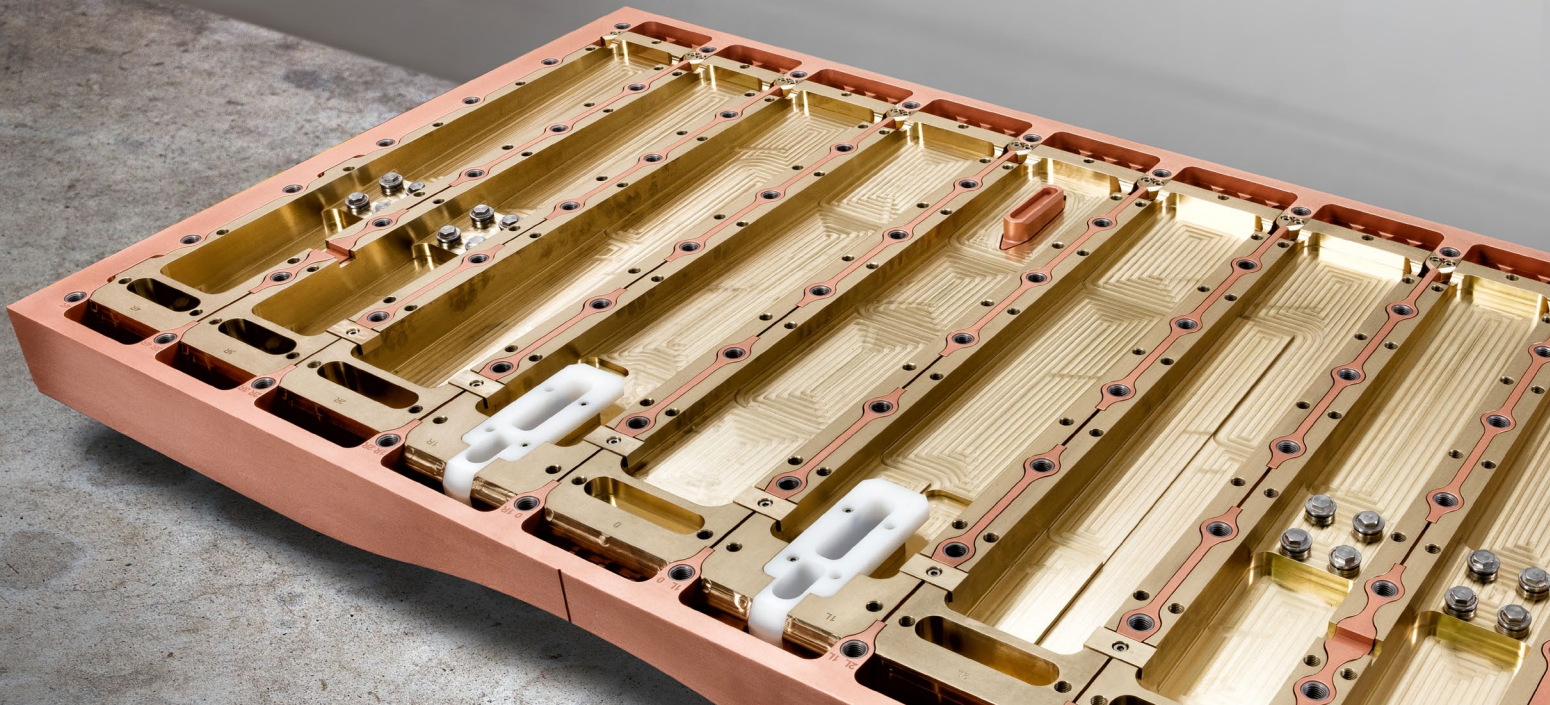


ATSM ADVANCED THIN SLAB MOULD

DESIGN CHALLENGE

- Improved thin-slab quality
- Lower operating costs and ease of maintenance
- Access to water-cooled copper surfaces for periodic inspection and cleaning
- Maintain operating practices



SOLUTION

- Improved copper plate design (Patent Applied)
- Reduced copper mold internal stress (Patent Applied)
- New anti-bulging system (Patent Applied)

ADVANTAGES

- Homogeneous copper plate temperature resulting in improved thin-slab quality
- Reduced meniscus bulging
- Easy installation
- No filler bars
- Complete access to water-cooled copper surfaces
- Compatible with existing water boxes and operating practices